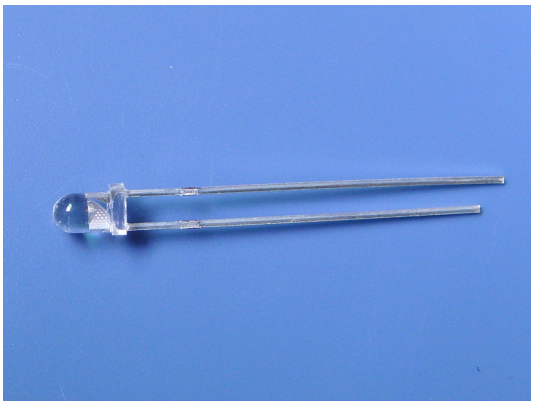
HONGLITRONIC
鸿利光电

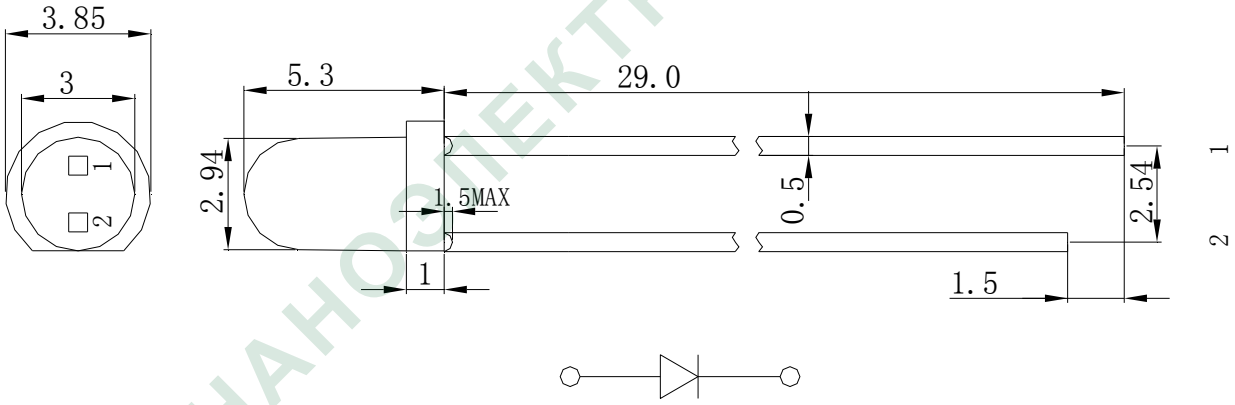
HL-304IR3C-L3



Features 特性

- Mechanically and spectrally matchend to the phototransistor. (机械和光谱与光电晶体管匹配)
- Rohs compliant. (符合 Rohs 认证)

Package Dimensions 封装尺寸



Description 描述

This devices are made with PIN GaAs.
LED 芯片组成元素为 PIN GaAs.

Tolerance Grade 公差等级	Dimension Tolerance (UNIT:mm) 尺寸误差 (单位:mm)			
	0.5~3	3~6	6~30	30~120
	±0.1	±0.2	±0.3	±0.5

Chip 晶片		Lens Color 透镜颜色
Material 材料	Emitting Color 发光颜色	Water Clear 无色透明
GaAs	/	

Selection Guide 选型向导

Part No	Radiant Intensity(mW/sr) 辐射强度(mW/sr) I_F=50mA		Viewing Angle 发光角度
	Min 最小值	Typ 典型值	2θ1/2
HL-304IR3C-L3	--	26	40

Note（注意）:

1. 2θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
   2θ1/2 是从光学中心线的发光强度为 1 / 2 的光学中心线的角度。

2.Tolerance of measurement of luminous intensity±15%.光强测量误差为±15%.

Electrical / Optical Characteristics at TA=25°C 光电特性 TA=25°C

Item 项目	Symbol 符号	Min 最小值	Typ 典型值	Units 单位	Test Conditions 测试条件
Forward Voltage 正向电压	V_F	1.2	1.5	V	I_F=50mA
Reverse Current 反向电流	I_R	--	10	uA	
Peak Spectral Wavelength 峰值光谱波长	λ_D	--	940	nm	
Spectral Bandwidth 光谱带宽	$\Delta\lambda$ 1/2	--	50	nm	

注意:

1.Tolerance of measurement of forward voltage±0.1V. 正向电压的测量误差为±0.1V.

2.Tolerance of measurement of peak Wavelength±2.0nm. 峰值波长的测量误差为±2.0nm.

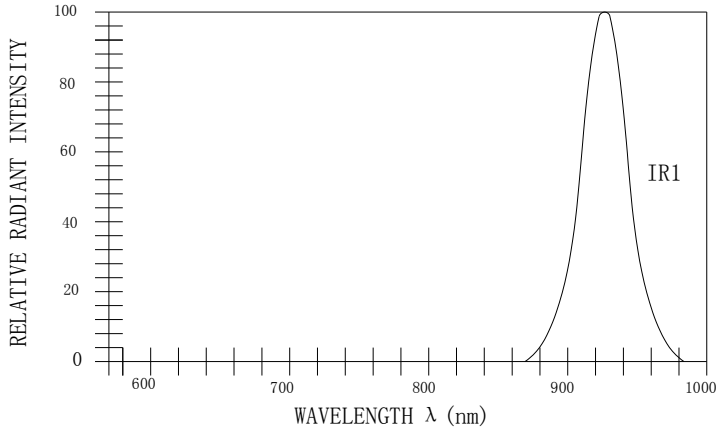
Absolute Maximum ratings at Ta=25℃光电特性在 Ta=25℃

Parameter 参数	Symbol 符号	IR1	Units 单位
Power Dissipation 消耗功率	P_t	100	mW
DC Forward Current 直流正向电流	I_F	50	mA
Peak Forward Current[1] 峰值正向电流[1]	I_{FS}	300	mA
Operating Temperature 操作温度	-30℃~80℃		
Storage Temperature 储存温度	-30℃~80℃		

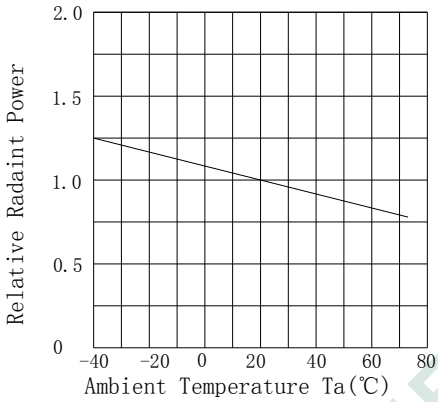
Note 注意:

1.IFP Conditions：Pulse Width≤10msec IFP 条件：脉冲宽度≤10msec

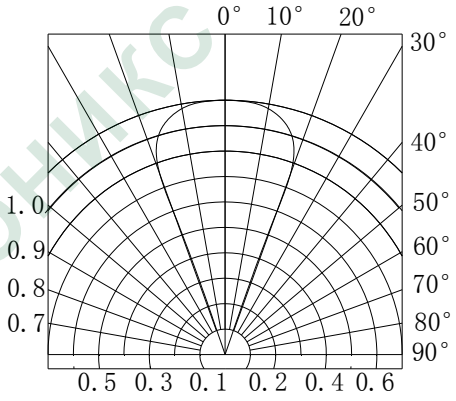
2.Tsol Conditions：3mm from the base of the epoxy bulb Tsol 条件：焊接位置离胶体底部 3 毫米



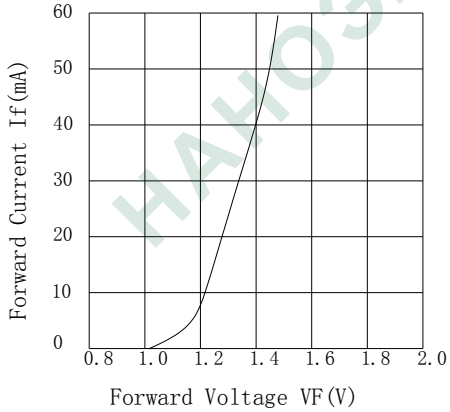
Forward Current vs.Forward Voltage

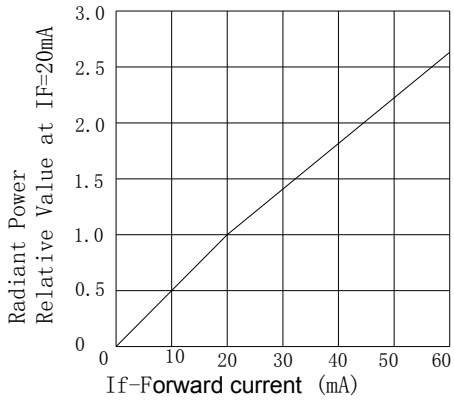


Radint Power Vs.Ambient Temperature



Spatial Distribution





Remarks 备注:

If special sorting is required (e.g.binning based on forward voltage or radiant intensity/luminous flux),the typical accuracy of the sorting process is as follows:

如果需要特殊的分类 (也就是分级基于正向电压或者辐射强度/光通量),分类过程的典型精度如下:

1. Radiant intensity/Luminous Flux:±15%.辐射强度/光通量:±15%.
2. Forward Voltage:±0.1V. 正向电压:±0.1V.

Note:Accuracy may depend on the sorting parameters. 注意:精度取决于分类参数

Soldering（焊接）：

1. Manual Of Soldering（手工焊接）
   The temperature of the iron tip should not be higher than 300℃and Soldering within 3 seconds per solder-land is to be observed.（烙铁最高温度不高于 300℃，焊接时间小于 3 秒）
2. DIP soldering (Wave Soldering)（波峰焊接:）
   Preheating:120℃~150℃,within 120~180 sec.(预热温度 120℃~150℃，小于 120~180 秒)
   Operation heating:245℃±5℃ within 5 sec.260℃(Max)
   操作温度：245℃±5℃小于 5 秒，最高温度不高于 260℃
   Gradual Cooling (Avoid quenching).
   过完波峰焊后应缓慢冷却.